

embodiment is effective for diminishing noise which arises in an inspection process and for improving inspection accuracy.--

Please replace the paragraph beginning at page 11, line 29, with the following rewritten paragraph:

--In the present embodiment, connection between the relay pin 18 and the burn-in board 12, connection between the relay pin 18 and the exchange board 22, and connection between the exchange board 22 and the socket terminals 24 are realized by means of soldering. However, these connections are not limited to soldering. For instance, pin sockets may be used for holding the relay pins 18 or the socket terminals 24.--

IN THE CLAIMS:

Please cancel claim 7.

Please amend claims 8, 9, and 10 as follows:

8. (Amended) An inspection apparatus for inspecting a plurality of semiconductor integrated circuits mounted on a base board, wherein the base board comprises:

a plurality of connection terminals electrically connected to terminals of an inspection main unit;

a plurality of wiring patterns connected to terminals of a semiconductor integrated circuit; and

a junction unit for changing the state of a junction formed between the connection terminals and the wiring pattern, wherein the junction unit includes a group of pin sockets each of which is interposed between each of a plurality of wiring patterns and a single connection terminal and/or a group of pin sockets each of which is interposed between each